

# ADVANCED PACKAGING CONFERENCE

## PACKAGING & TEST CHALLENGES TOWARDS HIGH RELIABILITY

12 - 13 NOV 2019 | ICM MUNICH, ROOM 14A

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### KEYNOTES:

**Jan Vardaman**  
President



**Emilie Jolivet**  
Semiconductor &  
Software Division  
Director



**Michael Schuldenfrei**  
Technology Fellow

**OPTIMAL+**

**Przemyslaw Gromala**  
Simulation  
Senior Expert



**Ramachandran Trichur**  
Director, Global Head  
of Advanced Packaging  
Market Segment



With the advent of IoT, Autonomous Driving and Smart Everything, the semiconductor industry is undergoing ever closer integration between the fields of More Moore and More Than Moore. The spiraling costs of transistor scaling are leading to highly inventive and challenging applications enabling improved PPAC (Power, Performance, Area, Cost), closer integration with alternative device types plus the need to bring Edge Computing into the local area compute arena. With all of these new integration and device approaches, Advanced Packaging is a key enabler for the continued growth of our industry.

**CONTACT:** SEMICONEuropa@semi.org

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# SEMICONDUCTORS DRIVE SMART

12-15 NOV 2019 | MUNICH, GERMANY

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## KEY FACTS



30% visitors represent  
engineering job functions



75% involved in  
purchasing decisions



35% are executives  
and senior managers



9,220 visitors from  
85 countries registered in 2018